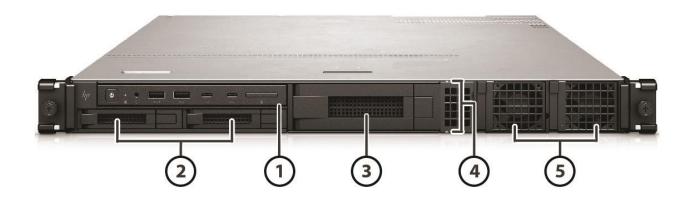
Overview

HP ZCentral 4R Workstation



Front view

- 1. Front I/O module options
 - Premium (optional shown here): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C®, Headset audio, (Left-most Type-A port has charging capability), Smart Card not supported
 - Standard (optional): power button, 4 USB 3.1 G1 Type-A (left-most Type-A port has charging capability), Headset audio, Smart Card not supported
- 2. 2 x 2.5" external drive bays
- 3. 1 x 3.5" external drive bay (can be configured with 1 x 3.5" drive or 2 x 2.5" drives)
- 4. Locator LED
- 5. 2 x external 675W PSU bays

ENTRY

Contains one (1) PSU 675W power supply.

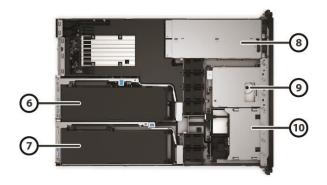
ENTRY REDUNDANT

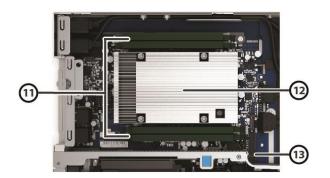
Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

HIGH END

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

Overview

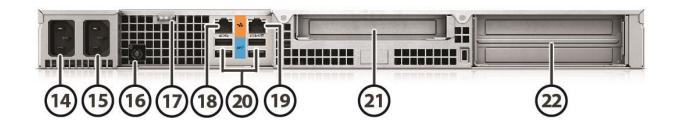




Internal views

- 6. Single Slot Riser (1 PCIe G3 x16); includes a single 6+2 auxiliary power cable
- 7. Dual Slot Riser (1 PCIe G3 x16; 1 PCIe G3 x16 wired as x8); includes an additional dual 6+2 auxiliary power cable
- 8. Power supply bays
- 9. 3.5" drive bay
- 10. Two 2.5" drive bays

- 11. Four DIMM slots; DDR4-2933 ECC Reg RAM
- 12. Intel® Xeon® Processors: W-2200 family
- 13. Two PCIe G3 x4 M.2 for SSDs



Rear view

- 14. Primary power supply cable connector
- 15. Secondary power supply cable connector
- 16. Rear power button
- 17. Padlock loop
- 18. 1GbE RJ-45 (AMT)

- 19. 1/2.5/5/10GbE RJ-45
- 20. 4x USB 3.1 G1 Type-A
- 21. Single Slot Riser (1 PCIe G3 x16)
- 22. Dual Slot Riser (1 PCle G3 x16; 1 PCle G3 x16 wired as x8)



Overview

Overview

Form Factor Operating Systems

1U Rackable Workstation

Preinstalled:

- Windows 10 Pro 64 for Workstations*
- Ubuntu Linux® 20.04**
- HP Linux-ready (minimal OS ready for customer OS installation)***

Supported:

- Red Hat® Enterprise Linux® Desktop 7.4 (Paper license with 1 year support)
- Red Hat® Enterprise Linux® Desktop 8.0 (Paper license with 1 year support)
- Ubuntu 18.04 LTS
- Ubuntu 20.04 LTS

Supported Version:

• HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.

For detailed Linux® OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix

- * Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- **Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- ***For detailed Linux® OS/hardware support information, see: http://www.hp.com/support/linux_hardware_matrix.

Note: In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows® 7 operating system on products configured with Intel® and AMD 7th Generation and forward processors or provide any Windows® 8 or Windows® 7 drivers on http://www.support.hp.com

Supported Components

Available Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz)¹	Intel® Turbo Boost Max Technology 3.0 (GHz)¹	TDP (W)
					Intel® Xe	on® W Proc	essors				
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	165
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120

¹Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

NOTE: Processors that do not have certain turbo functionality are denoted as N/A.

Available Processors Disclaimers

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



Supported Components

Expansion Slots

Slot 1 (SSR*): PCI Express Gen3 x16 from CPU

(see system board section for more details)

Slot 2 (DSR*): PCI Express Gen3 x16 from CPU - operates as x8 if Slot 3 is loaded

Slot 3 (DSR*): PCI Express Gen3 x16 (wired as x8) from CPU

M.2 Slot 1: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-

М

M.2 Slot 2: PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, 2280-D5-M, 22110-D5-M

*SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable

*DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and

configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary

power cable

Expansion Bays

2 external 2.5" bays

(see storage section for more details)

1 external 3.5" bay (can be configured with 1 x 3.5" drive or 2 x 2.5" drives)

Front I/O

Base: Power button with power/fault LED, Drive activity LED, 1 Headset audio port, 4
 HSB 2.1.61 Type A./1 charging applied 1.5A at 510

USB 3.1 G1 Type A (1 charging, provides 1.5A at 5V)

 Premium (optional): Power button with power/fault LED, Drive activity LED, 1 Headset audio port, 2 USB 3.1 G1 Type-A (1 charging, provides 1.5A at 5V), 2 USB 3.1 G2 Type-C[®]

(each provides 3A at 5V)

SD Card Reader is not supported

Internal I/O

1 USB 2.0 dual-port header

Rear I/O 4x USB 3.1 G1 Type-A*

1x 1/2.5/5/10GbE LAN port

1x 1GbE LAN port (supporting Intel AMT)

*All rear I/O motherboard USB-A ports are 0.9A at 5V

Interfaces Supported

4-channel SATA interface (6 @ 6.0 Gb/s)

USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)

On-board RAID Support

SATA RAID 0 Striped Array Configuration SATA RAID 1 Mirrored Array Configuration SATA RAID 10 Striped/Mirrored Configuration

Chassis Dimensions

Base footprint without front

bezel and rack brackets (H x W

x D)

With front bezel and rack

brackets (H x W x D)

H: 1.685" (42.8mm) W: 17.25" (438.15mm)

D: 24.61" (625mm)

H: 1.685" (42.8mm) W: 19.17" (486.81mm) D: 25.42" (645.70mm)

Packaged Dimensions H: 7.28" (185mm)

W: 23.22" (590mm) D: 32.48" (825mm)

Palletization Profile 2 units per layer x 10 layers = 20 units per pallet

1200x1000x1980mm(included pallet)

Rack Dimensions 1U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 10.7 kg (23.7 lbs.) Standard: 11.7 kg (25.9 lbs) Maximum: 13.6 kg (30 lbs)

Temperature Non-operating: -40° to 60° C (-40° to 140° F)

Operating: 5° to 35° C (40° to 95° F)

Supported Components

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C

(1.8° F) for every 305 m (1.000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb **Humidity**

Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (nonpressurized)

Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See Temperature for details.

Power Supply The ZCentral 4R 675W power supply efficiency report can be found at this link:

https://clearesult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-

D9ayoBFKnzPUpASigKGy2B-My6Ng?e=cPfbnt

ENTRY

Contains one (1) PSU 675W power supply.

ENTRY REDUNDANT

Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

HIGH-END

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

Workstation ISV Certifications See the latest list of certifications at

http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-Series CPU				
	Intel® Xeon® W-2295 3.0 2933 18C CPU	Υ	N		
	Intel® Xeon® W-2275 3.3 2933 14C CPU	Υ	N		
	Intel® Xeon® W-2265 3.5 2933 12C CPU	Υ	N		
	Intel® Xeon® W-2255 3.7 2933 10C CPU	Υ	N		
	Intel® Xeon® W-2245 3.9 2933 8C CPU	Υ	N		
	Intel® Xeon® W-2235 3.8 2933 6C CPU	Υ	N		
	Intel® Xeon® W-2225 4.1 2933 4C CPU	Υ	N		
	Intel® Xeon® W-2223 3.6 2933 4C CPU	Υ	N		

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



Supported Components

Storage / Hard Drives*

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations				
	1TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	QB576AA	
	4TB SATA 7200RPM Ent 3.5" HDD	Υ	Υ	K4T76AA	

*For storage drives, GB = 1 billion bytes. TB = one trillion bytes. Actual formatted capacity is less. Up to 35GB of disk space is reserved for system recovery software.

SATA Solid State Drives	HP Solid State Drives (SSDs) for Workstations	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 256GB SATA SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	N	Υ	Y6P08AA	
	HP 240GB SATA Ent SSD	Υ	Υ	T3U07AA	
	HP 480GB SATA Ent SSD	Υ	Υ	T3U08AA	
	HP 960GB SATA Ent SSD	Υ	Υ	1W6P8AA	
	HP 1920GB SATA Ent SSD	Υ	Υ	1W6P9AA	
	HP 512GB SATA SED OPAL2 SSD	N	Υ	N8T26AA	
	HP 1TB SATA SSD	Υ	Υ	F3C96AA	

PCIe Solid State Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z Turbo Drive Dual Pro				
	HP Z Turbo Drive Dual Pro 512GB TLC SSD	Υ	Υ	4YF61AA	
	HP Z Turbo Drive Dual Pro 1TB TLC SSD	Υ	Υ	4YF62AA	
	HP Z Turbo Drive Dual Pro 2TB TLC SSD	Υ	Υ	4YF63AA	
	HP Z Turbo 256GB TLC 4R Kit SSD	Υ	Υ	2E3R0AA	
	HP Z Turbo 512GB TLC 4R Kit SSD	Υ	Υ	2E3R1AA	
	HP Z Turbo 1TB TLC 4R Kit SSD	Υ	Υ	2E3R2AA	
	HP Z Turbo 2TB TLC 4R Kit SSD	Υ	Υ	2E3R3AA	
	HP Z Turbo 512GB SED TLC 4R Kit SSD	Υ	Υ	2E3R4AA	
	HP Z Turbo 256GB SED TLC 4R Kit SSD	Υ	Υ	2E3R5AA	

Supported Components

Intel® Virtual RAID on CPU (Intel® VROC) for NVMe	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® VROC NVMe SSD Standard Controller Module	N	Υ	3FJ80AA	1

NOTE 1: Enables RAID 0, 1 & 10

Graphics

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP miniDP-to-DP Adapter	Υ	Υ	2MY05AA	
HP miniDP-to-DP Adapter (12-pack)	Υ	N	2KW87A6	
Entry 3D				
NVIDIA® Quadro® P400 2GB Graphics	Υ	Υ	1ME43AA	1
Mid-range 3D				
NVIDIA® Quadro® P1000 4GB Graphics	Υ	Υ	1ME01AA	1
NVIDIA® Quadro® P2200 5GB Graphics	Υ	Υ	6YT67AA	1
High-End 3D				
NVIDIA® Quadro® RTX 4000 8GB Graphics	Υ	Υ	5JV89AA	1
Ultra High-End 3D				
NVIDIA® Quadro® RTX 5000 16GB Graphics	Υ	Υ	5JH81AA	2,3
NVIDIA® Quadro® RTX 6000 24GB Graphics	Υ	Υ	5JH80AA	2
NVIDIA® Quadro® RTX 8000 48GB Graphics	Υ	Υ	6NB51AA	2

NOTE 1: Dual graphics configuration requires addition of Dual Slot Riser and High End Chassis with 1350W PSU; Single Slot Riser includes single 6+2 pin auxiliary power cable. Dual Slot riser includes an additional dual 6+2 pin auxiliary power cable.

NOTE 2: Dual Graphics not Supported. Requires addition of Dual Slot Riser and High End Chassis with 1350W PSU. Dual Slot riser includes an additional dual 6+2 pin auxiliary power cable.

NOTE 3: The RTX 5000 can be configured with Redundant Power Supplies only when configured with processors with TDP ≤ 130W.

Supported Components

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
8GB (1x8GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ56AA/AT	1
16GB (1x16GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ54AA/AT	1
32GB (1x32GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ55AA/AT	1
64GB (1x64GB) DDR4- 2933 ECC Reg RAM	Υ	Υ	5YZ57AA/AT	1
Factory Configured System Memory Solutions				
8GB (1x8GB) DDR4				
16GB (1x16GB) DDR4				
16GB (2x8GB) DDR4				
24GB (3x8GB) DDR4				
32GB (2x16GB) DDR4				
32GB (4x8GB) DDR4				
64GB (2x32GB) DDR4				
64GB (4x16GB) DDR4				
	16GB (1x16GB) DDR4- 2933 ECC Reg RAM 32GB (1x32GB) DDR4- 2933 ECC Reg RAM 64GB (1x64GB) DDR4- 2933 ECC Reg RAM Factory Configured System Memory Solutions 8GB (1x8GB) DDR4 16GB (1x16GB) DDR4 16GB (2x8GB) DDR4 24GB (3x8GB) DDR4 32GB (2x16GB) DDR4 32GB (4x8GB) DDR4 64GB (2x32GB) DDR4	RGB (1x8GB) DDR4- 2933 ECC Reg RAM 16GB (1x16GB) DDR4- 2933 ECC Reg RAM 32GB (1x32GB) DDR4- 2933 ECC Reg RAM 64GB (1x64GB) DDR4- 2933 ECC Reg RAM Y Factory Configured System Memory Solutions 8GB (1x8GB) DDR4 16GB (1x16GB) DDR4 16GB (2x8GB) DDR4 24GB (3x8GB) DDR4 24GB (3x8GB) DDR4 32GB (2x16GB) DDR4 32GB (2x32GB) DDR4 64GB (2x32GB) DDR4	Configured Kit 8GB (1x8GB) DDR4- 2933 ECC Reg RAM Y Y 16GB (1x16GB) DDR4- 2933 ECC Reg RAM Y Y 32GB (1x32GB) DDR4- 2933 ECC Reg RAM Y Y 64GB (1x64GB) DDR4- 2933 ECC Reg RAM Y Y Factory Configured System Memory Solutions 8GB (1x8GB) DDR4 16GB (1x16GB) DDR4 16GB (2x8GB) DDR4 16GB (2x8GB) DDR4 32GB (2x16GB) DDR4 32GB (2x16GB) DDR4 32GB (4x8GB) DDR4 64GB (2x32GB) DDR4 16GB (2x32GB) DDR4	SGB (1x8GB) DDR4-2933 ECC Reg RAM Y Y 5YZ56AA/AT 16GB (1x16GB) DDR4-2933 ECC Reg RAM Y Y 5YZ54AA/AT 32GB (1x32GB) DDR4-2933 ECC Reg RAM Y Y 5YZ55AA/AT 64GB (1x64GB) DDR4-2933 ECC Reg RAM Y Y 5YZ57AA/AT Factory Configured System Memory Solutions 8GB (1x8GB) DDR4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 <td< td=""></td<>

NOTE 1: ONLY DDR4 RDIMMs are supported.

NOTE: Factory-configured CTO (xxxxxAV) and aftermarket AMO (xxxxxAA, xxxxxAT) HP memory part numbers designated as "2933" will be transitioned to use "3200" speed memory components. This does not affect HP part number availability, nor does it affect system performance or operation. All hardware configurations currently supporting HP memory part numbers designated as "2933" have been tested to work with "3200" memory and are fully-supported by HP under standard support terms.

Multimedia and Audio Devices

128GB (2x64GB) DDR4 128GB (4x32GB) DDR4 256GB (4x64GB) DDR4

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Realtek HD ALC3601 Audio	Υ	N		



Supported Components

Networking and Communications

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Intel® Ethernet I219-LM Single Port 1Gb NIC	Υ	N		
Integrated Marvell® AQC-107 Single Port 1/2.5/5/10GbE NIC	Υ	N		
Intel® I210-T1 Single Port 1GbE	Υ	Υ	E0X95AA	
Intel® X550-T2 Dual Port 10GbE NIC	Υ	Υ	1QL46AA	
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Υ	Υ	1C7Q2AA	

Racking and Physical Security

	Factory Configured	Option Kit		Support Notes
HP ZCentral 4R Front Bezel/Security	Υ	Υ	16G58AA	
HP ZCentral 4R Rail Rack Kit	Υ	Υ	16G60AA	

Input Devices

		Option Kit			
	Factory Configured	Option Kit	Part Number	Support Notes	
HP Wireless Business Slim Keyboard and Mouse	Υ	Υ	N3R88AA		
USB Business Slim Wired Keyboard	Υ	Υ	N3R87AA		
USB Premium Wired Keyboard	Υ	Υ	Z9N40AA		



Supported Components

Other Hardware

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ENERGY STAR® Certified Configuration	Υ	N		
HP ZCentral 4R 2 nd 675W Power Supply	Υ	Υ	1C9J6AA	
HP ZCentral 4R Dual PCIe Slot Riser Kit	Υ	Υ	16G54AA	
HP ZCentral 4R Power Cord Kit	Υ	Υ	1N1D4AA	
HP Z Premium Front I/O 2xUSB-A 2xUSB-C	Υ	Υ	16G59AA	
HP Serial Port and PS/2 Port	N	Υ	141K9AA	
HP Internal USB Port Kit		Υ	EM165AA	1
HP ZCentral 4R 2.5" Dual Drive Cage Adapter		Υ	16G55AA	
HP ZCentral 4R 2.5" Drive Carrier		Υ	16G56AA	
HP ZCentral 4R 3.5" Drive Carrier		Υ	16G57AA	

NOTE 1: The HP Internal USB Port Kit has a single USB 2.0 type A connector

Software

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP ZCentral Remote Boost	Υ	N		2
HP Sure Start Gen6	Υ	N		7
HP Sure Sense	Υ	N		3
HP Sure Click	Υ	N		4
HP PC Hardware Diagnostics UEFI	Υ	N		
HP PC Hardware Diagnostics Windows	Υ	N		
HP Performance Advisor	Υ	N		8
HP Client Security Manager Gen5	N	Υ		6
HP Manageability Integration Kit Gen4	N	Υ		5
Sobey Video Editing SW	N	Υ		1

NOTE 1: China Only

NOTE 2: HP ZCentral Remote Boost does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

NOTE 3: HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability. **NOTE 4:** HP Sure Click requires Windows 10. See https://bit.ly/2PrLT6A_SureClick for complete details.

NOTE 5: HP Manageability Integration Kit can be downloaded from

http://www.hp.com/go/clientmanagement.

NOTE 6: HP Client Security Manager Gen5 requires Windows and is available on the select HP Elite and Pro PCs.

NOTE 7: HP Sure Start Gen6 is available on select HP PCs and requires Windows 10.

NOTE 8: HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html

Operating Systems

Support Notes

Windows 10 Pro 64 for Workstations



Supported Components

Red Hat® Enterprise Linux® Desktop 7.4	1, 2
Red Hat® Enterprise Linux® Desktop 8.0	1, 2
Ubuntu 18.04 LTS	2
Ubuntu 20.04 LTS	2
NOTE 1: Paper license with 1 year support	

NOTE 2: For detailed Linux® OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix



System Technical Specifications

System Board

System Board Form

Factor L-Shaped

11.71 x 12.15 inches Single LGA2066 R4

Processor Socket
Chipset

Intel® Xeon® W Processor Family

Intel® C422 Chipset

Super I/O Controller

Nuvoton NPCD315HA0DX (SIO-15)

Memory Expansion

4 DDR4 memory slots

Slots Memory Type

Supported

DDR4, RDIMM (Registered), ECC

Memory Modes

Channel Interleaved

Memory Speed Supported 2933MT/s, 2666MT/s and 2400MT/s

Memory Protection

ECC available on data, parity on address and command

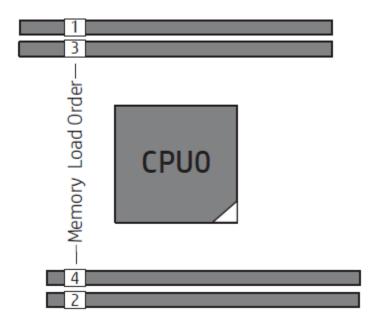
Maximum Memory Memory Configuration Supports up to 256GB

Memory configur

Only Registered DIMMs are supported.

(Supported)

Memory Load Order



Note on Maximum Memory Maximum memory capacities assume 64-bit operating systems such as Windows 10 Pro 64-bit, Windows 7 Professional 64-bit.

For systems installed with Microsoft Windows 7 (Ultimate, Enterprise or Pro), the maximum accessible system memory is 192GB

System Technical Specifications

PCI Express Connectors Slot 1 (SSR*): PCI Express Gen3 x16 supplied by CPU

Slot 2 (DSR*): PCI Express Gen3 x16 supplied by CPU (operates as x8 if Slot 3 is loaded)

Slot 3 (DSR*): PCI Express Gen3 x16 (wired as x8) supplied by CPU

M.2 Slot 1: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, 2280-D5-M, 22110-D5-M

M.2 Slot 2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, 2280-D5-M, 22110-D5-M

*SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable

*DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary

power cable

Supported Drive Interfaces

SATA

4 SATA @ 6GB/s, supports RAID 0,1, and 10

Factory integrated Intel® SATA RAID is Microsoft Windows only

Serial Attached SCSI Not supported

Factory Configured RAID

RAID 0 striped array

• RAID 1 mirrored array

• RAID 10 striped and mirrored array

*HW RAID functionality not supported by Linux®. Use SW RAID functionality provided in the Red Hat®

Operating system instead.

Integrated Graphics No

Network Controller Marvell AQtion AQC107 PCIe 1/2.5/5/10GBASE-T LAN

Intel® I219-LM PCIe GbE LAN supports the following management functionalities: Intel AMT11.12,

TXT, DASH 1.1, WOL, VLAN, Teaming and PXE 2.1

External SATA (eSATA) No

IDE connector No

Floppy connector No

Serial and PS2 1 internal header

2nd SerialNoParallelNoAUX IN (audio)NoIEEE 1394 Connector(s)No

USB Connector(s)

Front Front USB depends on which FIO module is selected:

Standard: 4 USB 3.1 G1 Type A (1 charging)

- Premium: 2 USB 3.1 G2 Type C[®], 2 USB 3.1 G1 Type A (1 charging)

Rear 4 USB 3.1 G1 Type A

1 USB 2.0 single-port header 1x USB 2.0 dual-port header

HD Integrated Audio

Realtek ALC3601-CG

Flash ROM

Yes



System Technical Specifications

Fan Headers Yes Front Control Panel/Speaker Yes

Header

CMOS Battery Holder -Yes

Lithium

Integrated Trusted Platform Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Module Common Criteria EAL4+ Certified

Yes

Convertible to FIPS 140-2 Certified mode through firmware v7.85

TPM Certified products list:

https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/

Power Supply Headers Power Switch, Power LED & Hard Drive LED Header

Yes

Clear Password Jumper Yes

1 internal header **Serial Port**

Parallel Port No

Keyboard/Mouse USB (PS/2 supported via AMO kit)

Hood Lock Header No **Hood Sensor Header** Yes

AUX OUT (audio) (Front Audio) Headset



System Technical Specifications

Power Supply

The HP ZCentral 4R Workstation contains up to two (2) 675 watt wide-ranging, active Power Factor Correction, 90% Efficient PSUs.

The 675W power supply efficiency report can be found at this link:

https://clearesult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-My6Ng?e=cPfbnt

ENTRY

Contains one (1) PSU 675W power supply.

ENTRY REDUNDANT

Contains two (2) 675W PSUs operating in redundant mode for a maximum system power of 675W.

HIGH END

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of 1350W (2x675W).

675W 90% Efficient, Custom PSU **Power Supply** (Wide-Ranging, Active PFC)

90-269 VAC

Operating Voltage Range 100-240 VAC 118 VAC Rated Voltage Range Rated Line Frequency 50-60 Hz 400 Hz **Operating Line Frequency**

47-66 Hz Range

393-407 Hz

9A @100-127 VAC 7A @ 118VAC **Rated Input Current**

4.5A @ 200-240 VAC

Heat Dissipation Typical = 1832 btu/hr (Configuration and software Max = 2647 btu/hr dependent)

40x40 mm variable speed **Power Supply Fan**

ENERGY STAR® Certified (Configuration dependent)

Yes

90% Efficient The power supply efficiency report can be found at this link:

80 PLUS® Compliant https://clearesult5.sharepoint.com/:b:/s/PLS/EavZwv9yq51Jnd6LV-D9ayoBFKnzPUpASiqKGy2B-

My6Ng?e=cPfbnt

FEMP Standby Power Compliant @115V Yes, 1 PSU only Yes, 1 PSU only

<1W in S5 - Power Off)

EuP Compliant @ 230V N/A for EMC Class A Equipment N/A for EMC Class A Equipment (<0.5 W in S5 - Power Off)

Power Consumption in sleep

mode

(as defined by ENERGY STAR®) - Suspend to RAM

<10W <10W

(S3)

(Instantly Available PC)

Built-in Self Test LED No No



System Technical Specifications

Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)

Yes

Yes



System Technical Specifications

System Configuration

Example ZCentral 4R	Processor	Intel Xeon W-2223 4C 3.6GHz						
Workstation	Memory	1x 8GB DDR4 2933 (Registered DIMM)						
Configuration #1	Graphics	1x NVIDIA Qu	adro P400					
ENERGY STAR®	Disks / Optical	1x HP Zturbo	M.2 512GB TLC	SSD				
Certified	Power Supply	1x 675W						
	Other	N/A						
		115 VAC 230 VAC					VAC	
Energy Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	45	.219	45.	379	45.	143	
	Windows Busy Typ(S0)	144.871		142.362		140.95		
	Windows Busy Max (S0)	150.762		149.580		148.992		
	Sleep (S3)	5.540	5.321	5.548	5.322	5.535	5.322	
	Off (S5)	2.945	2.524	3.13	3.005	3.112	2.998	
	Zero Power Mode (ErP)	0.300		0.314		0.301		
		11!	5 VAC	230	VAC	100	VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	154	4.287	154.833		154.027		
	Windows Busy Typ(S0)	494	4.299	485	.732	480	0.92	
	Windows Busy Max (S0)	514	4.399	510	.366	508	3.36	
	Sleep (S3)	18.902	18.155	18.929	18.129	18.885	18.158	
	Off (S5)	10.631	10.239	10.679	10.653	10.618	10.229	
	Zero Power Mode (ErP)	1.	023	1.0)71	1.0)27	



System Technical Specifications

Example ZCentral 4R	Processor	1x Intel Xeon	W-2245 8C 3.9	GHz			
Workstation	Memory	2x16GB DDR4-2933 (Registered DIMM)					
Configuration #2	Graphics	1x NVIDIA Qua	adro P2200				
ENERGY STAR®	Disks / Optical	1x ZTurbo 25	6GB M.2 SSD; 1	x 2TB 7200 S/	ATA Enterprise	3.5in HDD	
Certified	Power Supply	1x 675W					
	Other	N/A					
Energy Consumption		115	5 VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	53	.157	53.	368	52.	983
	Windows Busy Typ(S0)	272.91		270.65		267.35	
	Windows Busy Max (S0)	279.43		280.36		279.37	
	Sleep (S3)	5.314	5.375	5.328	5.371	5.321	5.381
	Off (S5)	2.945	2.908	2.943	2.9	2.963	2.902
	Zero Power Mode (ErP)	0.301		0.312		0.303	
		11!	5 VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	181	1.371	182.091		184.374	
	Windows Busy Typ(S0)	931	1.168	923	.457	912	.198
	Windows Busy Max (S0)	953	3.415	956	5.58	953	3.21
	Sleep (S3)	18.131	18.339	18.179	18.325	18.155	18.359
	Off (S5)	10.048	9.922	10.041	9.894	10.017	9.901
	Zero Power Mode (ErP)	1.	027	1.0	065	1.034	



System Technical Specifications

Example ZCentral 4R	Processor	1x Intel Xeon	W-2255 10C 3.	7GHz					
Workstation	Memory	4x 16GB DDR4-2933 (Registered DIMM)							
Configuration #3	Graphics	1x NVIDIA Quadro RTX4000							
	Disks/Optical	1x Zturbo 51	2GB M.2 SSD; 1:	x 4TB 7200 En	terprise SATA	HDD			
	Power Supply	1x 675W							
	Other	N/A							
Energy Consumption		115	5 VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
•	Windows Idle (S0)	56	5.77	57.	035	56.	.763		
	Windows Busy Typ(S0)	335.24		333.25		330.97			
	Windows Busy Max (S0)	345.36		344.89		344.67			
	Sleep (S3)	5.883	5.829	5.883	5.842	5.88	5.835		
•	Off (S5)	2.949	2.915	2.948	2.918	2.945	2.912		
	Zero Power Mode (ErP)	0.303		0.316		0.306			
		115	5 VAC	230	VAC	100	VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	193	3.699	194	.603	193.583			
	Windows Busy Typ(S0)	114	3.839	1137	7.049	112	9.27		
	Windows Busy Max (S0)	117	78.36	117	6.76	117	6.01		
	Sleep (S3)	20.072	19.888	20.072	19.932	20.062	20.072		
	Off (S5)	10.061	9.945	10.058	9.956	10.048	10.061		
	Zero Power Mode (ErP)	1.	034	1.0)78	1.0) 144		



System Technical Specifications

Example ZCentral 4R	Processor	1x Intel Xeon	W-2295 18C 3	3.0GHz			
Workstation	Memory	1x 32GB DDR4-2933 (Registered DIMM)					
Configuration #4	Graphics	1x NVIDIA RTX	(8000				
	Disks / Optical	2x ZTurbo 2TE	3 M.2 SSD; 2x	ZTurbo 2TB Z	Dual Pro PCIe	SSD; 4x 1TB 2.	5in SATA SSD
	Power Supply	2x 675W PSU					
	Other	N/A					
Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	60.4	189	60.	889	60.	413
	Windows Busy Typ(S0)	464.213		458.512		461. 441	
	Windows Busy Max (S0)	495.789		487.213		491.220	
	Sleep (S3)	5.893	5.819	5.990	5.831	5.887	5.412
	Off (S5)	3.312	3.012	3.418	3.111	3.303	3.045
	Zero Power Mode (ErP)	0.523		0.774		0.517	
		115	VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	206.	388	207.753		206.129	
	Windows Busy Typ(S0)	1583	.894	1563	3.984	1574	.4367
	Windows Busy Max (S0)	1691	.632	1662	2.370	1676	5.043
	Sleep (S3)	20.107	19.854	20.437	19.895	20.086	18.465
	Off (S5)	11.301	10.277	11.662	10.615	11.269	10.389
	Zero Power Mode (ErP)	1.78	344	2.6	411	1.7	641

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

System Technical Specifications

DECLARED NOISE EMISSIONS

Declared Noise Emissions	(Entry-level and High-end	configurations)					
System Configuration	Processor Info	Intel® Xeon® W-2255 3.7	7GHz 2933MHz 10C CPU				
(Entry level)	Memory Info	256GB (4x64GB) DDR4-2933 ECC Reg RAM					
	Graphics Info	1-NVIDIA® Quadro® RTX 4000					
	Disks/Optical	1-4TB SATA 7200RPM 3.5" HDD / 2-1TB 2.5" SSD / 2-2TB PCIe M.2 SSD					
	Power Supply	Single 675W					
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)				
	Idle	4.9	34				
	Hard drive Operating (random reads)	4.9	34				

NOTE: Higher noise levels may be experienced with non-HP approved graphic card(s). Some consumer graphics cards have side blowing fans that may heat up thermal sensor(s) on the mother board causing fans to ramp.



System Technical Specifications

ENVIRONMENTAL DATA

Environmental Requirements

Temperature Non-operating: -40° to 60° C (-40° to 140° F)

Operating: 5° to 35° C (40° to 95° F)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1°C (1.8°F) for every 305 m (1,000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Shock (non-repetitive) Operating: 1/2-sine: 40q, 2-3ms (~62 cm/sec)

Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

Non-operating square: 422 cm/s, 20g

Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g2/Hz

Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information.

Hard Drives Screw-mounted

Expansion Cards Expansion card cage removal/insertion into system is tool-less

Expansion card access requires removal of screw-mounted retainer bracket

Processor Socket Tool-less

Blue User Touch Points Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

Memory DIMM Connectors Tool-less **System Board** Screw-mounted

Dual Color Power/Failure Yes

LED

HDD Activity LED Yes

Note: HDD Activity LED is not dual-color

Configuration Record SW Yes

Restore CD/DVD Set

Padlock Support

Over-Temp Warning on Yes, at POST screen on reboot

Screen

Restores the computer to its original factory shipping image; can be obtained via HP Support.

Yes, causes a fail-safe power off when held for 4 seconds **Dual Function Front**

Power Switch

Yes (optional): Locks top cover and secures chassis from theft 7.0 mm (0.2756 in) diameter padlock loop at rear of system

Cable Lock Support Yes. Kensington Cable Lock (optional): Secures chassis from theft

3 mm x 7 mm slot at rear of system

System Technical Specifications

Universal Chassis Clamp No

Lock Support

Chassis Interlock Sensor Yes

Sensor detects when the access panel has been removed. The access panel must be installed for the

system to power ON.

Serial, USB, Audio,

Network. Enable/Disable

Port Control

Yes, enables or disables serial, USB, audio, and network ports

Removable Media Write/Boot Control Yes, prevents ability to boot from removable media on supported devices (and can disable writes to

media)

Power-On Password

Yes, prevents an unauthorized person from booting up the workstation

Setup Password

Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on

System PCA

Yes

NIC LEDs (integrated)

Yes

(Green & Amber) **CPUs and Heatsinks**

A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Power Supply Diagnostic Yes

LED

Solid Green (OK); Blinking Green (Standby); Red (Fault); Off (No AC Power/PSU Failure)

Front Power Button Yes, ACPI multi-function

Rear Power Button Yes **System Locator LED** Yes. blue

Front Power LED Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

LED

Yes

Flash Recovery

Internal Speaker

System/Emergency ROM Recovers corrupted system BIOS.

Air cooled forced convection heatsinks **Cooling Solutions Power Supply Fan** 40 mm x 40 mm x 28 mm (non-serviceable) 40 mm x 40 mm x 56 mm (serviceable) **Chassis Fans**

HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot and is

available as a download from HP Support.

Access Panel Key Lock

ACPI-Ready Hardware

Advanced Configuration and Power Management Interface (ACPI).

- Allows the system to wake from a low-power mode.
- Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Infineon TPM 2.0 Certified

Chip

Integrated Chassis

Handles

No

Power Supply Tool-less

PCIe Card Retention Yes, rear (all), middle (all), front (full-length cards with extender)

Flash ROM Yes **Diagnostic Power Switch** Yes

LED on board



System Technical Specifications

Clear Password Jumper Yes **Clear CMOS Button** Yes **CMOS Battery Holder** Yes

BIOS

BIOS 32-bit Services

Standard BIOS 32-bit Service Directory Proposal v0.4

PCI 3.0 Support

Full BIOS support for PCI Express through industry standard interfaces.

ATAPI

ATAPI Removable Media Device BIOS Specification Version 1.0.

BBS

BIOS Boot Specification v1.01.

WMI Support

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On

Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Recovers system BIOS in corrupted Flash ROM.

Flash Recovery with

Video **Replicated Setup**

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigUtility.exe

utility can then replicate these settings on machines being deployed without entering Computer

Configuration Utility (F10 Setup).

SMBIOS

System Management BIOS 3.2, for system management information. Disables the ability to boot from removable media on supported devices.

Boot Control Memory Change Alert

Alerts management console if memory is removed or changed.

Thermal Alert

Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash

Provides secure, fail-safe ROM image management from a central network console.

ACPI (Advanced

Allows the system to enter and resume from low power modes (sleep states).

Configuration and Power Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload.

Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

Instantly Available PC (Suspend to RAM - ACPI Allows for very low power consumption with quick resume time.

sleep state \$3)

Remote System Installation via F12 (PXE 2.1) (Remote Boot from

Server)

ROM revision levels

Allows a new or existing system to boot over the network and download software, including the operating system.

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System Technical Specifications

Allows management SW to read revision level of the system board. **System board revision**

level Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics Assesses system health at boot time with selectable levels of testing.

Auto Setup when new hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory. **Asset Tag**

Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. **Per-slot Control Adaptive Cooling** Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED.

Pre-boot Diagnostics Industry Standard Specification Support **Industry Standard**

(Power-on Self-Test)

UEFI Specification

Revision Supported by the BIOS

Revision

PMM

ACPI Advanced Configuration and Power Management Interface, Version 5.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0

PCI Express PCI Express Base Specification, Revision 3.0

POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM

Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified

FIPS 140-2 Certified

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

> Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 G1 Specification Universal Serial Bus Revision 3.1 G2 Specification

SMBIOS System Management BIOS Reference Specification, Version 3.2 System Technical Specifications

Social and Environmental Responsibility

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be **Declarations** labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program (CECP)
- The ECO declaration (TED)
- The ZCentral 4R is registered EPEAT® Gold in the US and Canada. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

Batteries

The battery in this product complies with EU Directive 2006/66/EC

Battery mass: 3g

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Restricted Material Usage

This product meets the material restrictions specified in HP's General Specification for the Environment. HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis.

Low Halogen Statement

This product contains low-halogen printed circuit boards.

End-of-Life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Sustainable Impact Report

Eco-label certifications ISO 14001 certificates

Additional Information

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.

Packaging

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials

System Technical Specifications

- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- · Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting
- A multi-unit eco packaging option is available to institutional customers that uses less packaging material or has a lower volume footprint than conventional single-unit packaging. Please contact your sales representative for additional details.

Packaging Materials Internal External

Cushions and plastic bags made of low density polyethylene (LDPE). Outer carton, accessories carton, and insert made of corrugated paper board.



System Technical Specifications

Manageability

Industry Standard Specifications

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel® LAN on motherboard)

Technology (AMT)

Intel Active Management Intel® Active Management Technology (AMT) 11.12

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.12 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- NEW: Hardware Alerting (with special enablement for RPSU alerting)
- **Agent Presence**
- **System Defense Filters**
- Serial Over LAN (SOL)
- **USB Redirect (Media Redirection)**
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- **IPv6** Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC

Remote Memory Dump Command – Creates memory dump for debug

Intel® vPro™ Technology The HP ZCentral 4R Workstation supports Intel® vPro™ technology when configured as outlined below:

- Intel® Xeon® processor W-2200 product family featuring Intel® vPro™ Technology
- Intel® C422 chipset

Intel® I219LM GbE LAN

Remote Manageability Software Solutions

The HP ZCentral 4R Workstation is supported on the following optional remote manageability software consoles:

- **HP ZCentral Connect**
- Ivanti Management Suite
- Microsoft System Center Configuration Manager

For questions or support for manageability needs, please visit

http://www.hp.com/go/easydeploy



System Technical Specifications

System Software Manager

For easy deploy questions or support for SSM, please visit: http://www.hp.com/go/ssm

Service, Support, and Warranty

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. **NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Product Change Notification

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors Intel® Xeon® W-2223 3.6 2666 4C CPU

Intel® Xeon® W-2225 4.1 2933 4C CPU Intel® Xeon® W-2245 3.9 2933 8C CPU

Hard Drives 1TB SATA 7200RPM Ent 3.5" HDD

1TB HP Z Turbo M.2 TLC 4R Kit SSD

Graphics N/A

Technical Specifications - Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz) ¹	Intel® Turbo Boost Max Technology 3.0 (GHz) ¹	TDP (W)
					Intel® Xe	on® W Proc	essors				
Intel® Xeon® W-2295 processor	18	3.0	24.75	2933	YES	512GB	YES	YES	3.8, 4.6	4.8	165
Intel® Xeon® W-2275 processor	14	3.3	19.25	2933	YES	512GB	YES	YES	4.1, 4.6	4.8	165
Intel® Xeon® W-2265 processor	12	3.5	19.25	2933	YES	512GB	YES	YES	4.3, 4.6	4.8	165
Intel® Xeon® W-2255 processor	10	3.7	19.25	2933	YES	512GB	YES	YES	4.3, 4.5	4.7	165
Intel® Xeon® W-2245 processor	8	3.9	16.5	2933	YES	512GB	YES	YES	4.5, 4.5	4.7	155
Intel® Xeon® W-2235 processor	6	3.8	8.25	2933	YES	512GB	YES	YES	4.3, 4.6	N/A	130
Intel® Xeon® W-2225 processor	4	4.1	8.25	2933	YES	512GB	YES	YES	4.5, 4.6	N/A	105
Intel® Xeon® W-2223 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120

¹Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

NOTE: Processors that do not have certain turbo functionality are denoted as N/A.



Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

SATA Hard Drives for HP Workstations 1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M hours

Reliability (MTBF) 2.0M hour Rated Power On Hours 8760/yr Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365 operation

Physical Size (Height) 1 in; 2.54 cm
Physical Size (Width) 4 in; 10.17 cm
Media Diameter 3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

YES

Synchronous Transfer

Rate (Maximum)

128MB

Up to 600MB/s*

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average0.32ms*
7.45ms*Full Stroke14.2ms*

settling)

Buffer

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

Enterprise Class High Reliability

Features

*Actual performance may vary.



Technical Specifications - Hard Drives

2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 2TB **Protocol** SATA **Form Factor** 3.5" Controller AHCI Reliability (MTBF) 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure** <0.62%

Rate (based on Rated

POH)

Rated for 24/7/365 YES

operation

Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in; 10.17 cm **Media Diameter** 3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

128MB Buffer

Seek Time (typical Single Track 0.48ms* reads, includes Average 7.7ms* controller overhead, **Full Stroke** 14.2ms*

including settling) Operating Temperature

41° to 140° F (5° to 60° C) **Performance**

Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s* **High Reliability**

Enterprise Class

Features

*Actual performance may vary.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 4TB

Height 0.275 in; 0.7 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, Single Track 0.7ms* includes controller **Average** 8.5ms* overhead, including **Full Stroke** 15.7ms* settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 140° F (0° to 60° C)

*Actual performance may vary.

Technical Specifications - Hard Drives

SATA	SSDs	for	HP
Work	statio	ns	

HP 256GB SATA 6Gb/s SSD

Capacity 256GB Protocol **SATA Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

192TBW (TB Written) **Endurance**

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530MB/s (max)* **Sequential Write** 500MB/s (max)* **Random Read** 55K IOPS (max)* **Random Write** 83K IOPS (max)*

HP 512GB SATA 6Gb/s SSD

Capacity 512GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

388TBW (TB Written) **Endurance**

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s*

Sequential Write 500 MB/s* **Random Read** 95K IOPS* **Random Write** 83K IOPS*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP 11	ΓB SATA	6Gb/	s SSD
--------------	---------	------	-------

Capacity1TBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)*

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530 MB/s*
Sequential Write 500 MB/s*
Random Read 95K IOPS*
Random Write 83K IOPS*

HP 1920GB SATA 6Gb/s SSD

Capacity 1920GB

 Protocol
 SATA

 Form Factor
 2.5"

 Controller
 AHCI

 NAND Type
 3D TLC

Endurance 4,400TBW (TB Written)

Reliability (MTTF) 2.0M hours
Physical Size (Height) 0.28 in; 0.7 cm
Physical Size (Width) 2.5 in; 6.36 cm
Interface SATA 6Gb/s

Synchronous Transfer

Up to 600MB/s (Sequential Read)*

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 5340MB/s*

Sequential Write 460 MB/s*
Random Read 93K IOPS*
Random Write 74K IOPS*

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP En	terpris	e Class
240GI	SATA	SSD

Capacity 240GB **Protocol SATA** 2.5" **Form Factor** Controller AHCI **NAND Type** 3D TLC

Endurance 2,190TBW (TB Written)

Reliability (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in: 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

32° to 158° F (0° to 70° C)

Operating Temperature Performance

Sequential Read 540 MB/s* **Sequential Write** 310 MB/s* **Random Read** 93K IOPS*

Random Write 48K IOPS*

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection

HP Enterprise Class 480GB SATA SSD

Capacity 480GB **Protocol** SATA **Form Factor** 2.5" Controller AHCI **NAND Type** 3D TLC

Endurance 4,380TBW (TB Written)

Reliability (MTTF) 2.0M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA **Synchronous Transfer** Up to 600MB/s*

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 540 MB/s*

> **Sequential Write** 460 MB/s* **Random Read** 93K IOPS* **Random Write** 74K IOPS*

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection

Capacity 960GB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP Enterprise Class 960GB SATA SSD Protocol SATA
Form Factor 2.5"
Controller AHCI
NAND Type 3D TLC

Endurance 8,760TBW (TB Written)

Reliability (MTTF)2.0M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterface6Gb/s SATASynchronous TransferUp to 600MB/s*

Rate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 540 MB/s*

Sequential Write 460 MB/s*
Random Read 93K IOPS*
Random Write 74K IOPS*

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Performance PCIe SSDs for HP Workstations HP Z Turbo Drive G2 256GB TLC SSD and 256GB SED TLC SSD Capacity 256GB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC
Endurance 200TB
Reliability (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400 MB/s*

Sequential Write 2500 MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

HP Z Turbo Drive G2 512GB TLC SSD and 512GB SED TLC SSD
 Capacity
 512GB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

 SED Support
 Opal 2

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 2900 MB/s*
Random Read 460 K IOPS*
Random Write 500K IOPS*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP	Z 1	url	bo	Drive	9 G2
1TI	ВТ	LC S	SSI	D	

Capacity1TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s*
Random Read 580K IOPS*
Random Write 500K IOPS*

HP Z Turbo Drive G2 2TB TLC SSD

 Capacity
 2TB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 500TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface M.2: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, D5

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s *
Random Read 600K IOPS*
Random Write 500K IOPS*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

HP Z	Turbo	Drive	Dual
Pro 5	12GB	SSD	

Capacity 512GB (one M.2 PCIe NVMe module)

Protocol PCIe

Form Factor M.2 in Half-height, half-length card

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x8 electrical x8 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 2900 MB/s*
Random Read 460 K IOPS*
Random Write 500K IOPS*

*Actual performance may vary.

HP Z Turbo Drive Dual Pro 1TB SSD

Capacity 1TB (one M.2 PCIe NVMe module)

Protocol PCIe

Form Factor M.2 in Half-height, half-length card

Controller NVMe NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x8 electrical x8 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s*
Random Read 580K IOPS*
Random Write 500K IOPS*

*Actual performance may vary.

HP Z Turbo Drive Dual Pro 2TB SSD

Capacity 2TB (one M.2 PCIe NVMe module)

Protocol PCIe

Form Factor M.2 in Half-height, half-length card

Controller NVMe **NAND Type** 3D TLC

Endurance 500TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x8 electrical x8 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3500 MB/s*

Sequential Write 3000 MB/s *
Random Read 600K IOPS*
Random Write 500K IOPS*



^{*}Actual performance may vary.

Technical Specifications - Graphics

GRAPHICS

NVIDIA® Quadro® P400 2GB Graphics **Form Factor** Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P400 Graphics Card

GPU: 256 CUDA cores Power: 30 Watts Cooling: Active

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 64-bit Memory Bandwidth: 32 GB/s

Connectors 3mDP 1.4 Outputs*

Maximum Resolution DisplayPort™ 1.4:

up to 3x 4096 x 2160 x 24 bpp @ 60Hz
 up to 1x 5120 x 2880 x 24 bpp @ 60Hz
 supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 3 mDP 1.4 Connectors

Shading Architecture Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics

Drivers

Microsoft Windows 10

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes *P400, P600 and P1000 only have mini-DisplayPort™ (mDP) video ports.

Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters

included

After market option kit:Two mDP-to-DP Adapters included

Additional mDP-to-DP Adapters are available as Factory Configuration or

Option Kit accessories:

2MY05AA - HP miniDP-to-DP Adapter Cables

- 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables

Technical Specifications - Graphics

NVIDIA® Quadro® P1000 4GB Graphics Form Factor Dimensions:2.713" H x 5.7" L

Single Slot, Low Profile Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P1000 Graphics Card

GPU: 640 CUDA cores Power: 47 Watts Cooling: Active

Bus Type PCI Express 3.0 x16

Memory Size: 4 GB GDDR5, 2500 MHz

Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth

Connectors 4mDP 1.4 Outputs* **Maximum Resolution** DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP 1.4 Connectors

Shading Architecture Full Microsoft DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulkan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics

Drivers

Microsoft Windows 10

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes *P400, P600 and P1000 only have mini-DisplayPort™ (mDP) video ports.

Factory Configured (Z4 G4/ Z6 G4/ Z8 G4 Workstations): No adapters

included

After market option kit:Two mDP-to-DP Adapters included

Additional mDP-to-DP Adapters are available as Factory Configuration or

Option Kit accessories:

- 2MY05AA - HP miniDP-to-DP Adapter Cables

- 2KW87A6 - HP (Bulk 12) miniDP-to-DP Adapter Cables



Technical Specifications - Graphics

NVIDIA® Quadro® P2200 Form Factor 5GB Graphics

Dimensions: 4.4"H x 7.9"L

Single Slot Weight: 260 grams

Graphics Controller NVIDIA® Quadro® P2200 Graphics Card

Power: 75 Watts Cooling: Active

Bus Type PCI Express 3.0 x16 **Memory** Size: 5GB GDDR5x

Memory Bandwidth: 200 GB/s

Memory Width: 160-bit

Connectors 4x DisplayPort™ 1.4

Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included

Additional DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to

Dual-Link DVI adapters available as accessories.

Maximum Resolution DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- up to 4x 4096 x 2160 x 24 bpp @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features 12-bit internal display pipeline (hardware support for 12-bit scanout on

supported panels, applications and connection)

Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

NVIDIA® Mosaic and nView.

Display Output Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

Shading Architecture

Supported Graphics APIs OpenGL® 4.6

DirectX® 12.0 Vulkan 1.1

Shader Model 5.1

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

software

Available Graphics

Drivers

Microsoft Windows 10

Linux® - Full OpenGL® implementation, complete with NVIDIA® Quadro® and

ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Technical Specifications - Graphics

Notes

- Quadro P2000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately.
- 2. Quadro P2000 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

NVIDIA® Quadro® RTX 4000 8GB Graphics

Form Factor

Full-Height Single Slot (4.4" Height x 9.5" Length)

Weight: 550 grams / 1.21 lbs

Graphics Controller NVIDIA® Quadro® RTX 4000 Graphics

GPU: 2304 NVIDIA® CUDA® Parallel Processing Cores Power: 160 Watts (125W graphics + 35W USB-C® PD)

Cooling: Active

Memory 8GB GDDR6

Memory Bandwidth: Up to 416 GB/s

Memory Width: 256-bit

Connectors 3x DisplayPort™ 1.4 and 1x VirtualLink

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link

DVI adapters available as accessories.

Maximum Resolution DisplayPort™ 1.4:

- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution²

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- up to 4x 3840 x 2160 x 24 bpp @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features Advanced support fo

Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort™, and HDMI connectors NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

Display Outputs¹ Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

Supported Graphics APIs DirectX°12, OpenGL° 4.6, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran

Technical Specifications - Graphics

Available Graphics

Drivers

Windows® 10 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

1- Supports up to a total of 4 displays

2- Display must be capable of DSC or 2-cabled solution to obtain

this resolution

NVIDIA® Quadro® RTX 5000 16GB Graphics **Form Factor**

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 975 grams + 75 grams extender

Graphics Controller NVIDIA® QUADRO® RTX 5000

GPU: 3072 CUDA cores, 384 Tensor Cores, 48 RT Cores Power: 265 Watts (230W graphics + 35W USB-C® PD)

Cooling: Active

Memory

16GB GDDR6

Memory Bandwidth: Up to 448 GB/s ECC Memory (disabled by default)

Connectors

4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink

1x 8-pin and 1x 6-pin auxiliary power connectors

1x NVLink

Quadro Sync connector (compatible with Quadro II Sync)

3-pin mini-DIN connector via optional bracket

4-pin header for stereo signal

After market option Kit: no power adapter included with card.

DisplayPort™ to VGA, DisplayPort™ to DVI (single-link and dual-link), and

DisplayPort™ to HDMI adapters available as accessories.

Maximum Resolution

DisplayPort™ 1.4:

- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution²

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz- up to 4x 4096 x 2160 x 24 bpp @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features

HDR support over DisplayPort™ 1.4 (SMPTE 2084/2086, BT. 2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b

HEVC Encode)

HDCP 2.2 support over DisplayPort[™] and HDMI connectors

NVIDIA 3D Vision™ technology

NVIDIA Mosaic and nView Desktop Management

Display Outputs

Maximum number of displays - 4 direct attached monitors

Technical Specifications - Graphics

Maximum number of monitors across all available outputs is 4

GPU Architecture NVIDIA® Turing

Supported Graphics APIs DirectX®12, OpenGL® 4.6

Developer API support includes: CUDA C, CUDA C++, DirectCompute,

OpenCL™, Java, Python, and Fortran

Available Graphics Drivers

Windows® 10 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included

After market option kit: No adapters included

NVIDIA® Quadro® RTX 6000 24GB Graphics

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 995 grams + 75 grams extender

NVIDIA® QUADRO® RTX 6000 Graphics Controller

> GPU: 4608 CUDA Cores, 576 Tensor Cores, 72 RT Cores Power: 295 Watts (260W graphics + 35W USB-C® PD)

Cooling: Active

24GB GDDR6 Memory

> Memory Bandwidth: Up to 672 GB/s ECC Memory (disabled by default)

Connectors 4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink

1x 8-pin and 1x 6-pin auxiliary power connectors

1x NVLink

Quadro Sync connector (compatible with Quadro II Sync)

3-pin mini-DIN connector via optional bracket

4-pin header for stereo signal

After market option Kit: no power adapter included with card.

DisplayPort[™] to VGA, DisplayPort[™] to DVI (single-link and dual-link), and

DisplayPort™ to HDMI adapters available as accessories.

Maximum Resolution DisplayPort™ 1.4:

- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution²

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz

- up to 4x 4096 x 2160 x 24 bpp @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter):

Technical Specifications - Graphics

- up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features HDR support over DisplayPort™ 1.4 (SMPTE 2084/2086, BT.

2020) (4K @ 60 Hz 10b/12b HEVC Decode, 4K @ 60 Hz 10b

HEVC Encode)

HDCP 2.2 support over DisplayPort™ and HDMI connectors

NVIDIA 3D Vision™ technology

NVIDIA Mosaic and nView Desktop Management

Display Outputs Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

GPU Architecture NVIDIA® Turing

Supported Graphics APIs DirectX®12, OpenGL® 4.6

Developer API support includes: CUDA C, CUDA C++, DirectCompute,

OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows® 10 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Factory Configured (Z4/Z6/Z8 G4 Workstation): No adapters included

After market option kit: No adapters included



Technical Specifications - Graphics

NVIDIA® Quadro® RTX 8000 48GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1070 grams / 2.35 lbs

Graphics Controller NVIDIA® Quadro® RTX 8000 Graphics

GPU: 4608 CUDA Cores, 576 Tensor Cores, 72 RT Cores

Power: 295 Watts Cooling: Active

Memory 48GB GDDR6 memory

Memory Bandwidth: Up to 672 GB/s

Memory Width: 384-bit

Connectors 4x DisplayPort™ 1.4 with HDR support and 1x VirtualLink

1x 8-pin and 1x 6-pin auxiliary power connectors

1x NVLink

Quadro Sync connector (compatible with Quadro II Sync)

3-pin mini-DIN connector via optional bracket

4-pin header for stereo signal

After market option Kit: no power adapter included with card.

DisplayPort™ to VGA, DisplayPort™ to DVI and DisplayPort™ to HDMI

adapters available as accessories.

Maximum Resolution DisplayPort™ 1.4:

- up to 2x 7680 x 4320 x 24 bpp @ 60Hz with DSC or 2 cable solution²

- up to $4x\,5120\,x\,2880\,x\,24\,bpp$ @ 60Hz - up to $4x\,4096\,x\,2160\,x\,24\,bpp$ @ 120Hz

- supports High Bit Rate 3 (HBR3) and Multi-Stream Transport (MST)

HDMI 2.0 (requires DP to HDMI adapter): - up to 4096 x 2160 x 24 bpp @ 60Hz

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort™ and HDMI connectors NVIDIA® 3D Vision™ and other 3D stereo technologies

NVIDIA® Mosaic and nView

Display Outputs¹ Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available outputs is 4

Supported Graphics APIs DirectX°12, OpenGL° 4.6, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute,

OpenCL™, Java, Python, and Fortran

Available Graphics Windows® 10 64-bit

Drivers Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site: http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

Integrated Intel I219 PCIe Connector **GbE Controller**

RJ-45 Intel I219 GbE platform LAN connect networking controller Controller

Data Rates Supported Boot ROM Support Connect Speed LED

Indicators

10/100/1000 Mbps

PXE, UEFI, iSCSI Boot Link/Activity LED

Off = No link Blinking = Activity

Speed LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Wake-On-LAN, Intel® Active Management Technology™ (AMT) 11.12

Integrated Marvell AQC- Connector 107

RJ-45

Controller Marvell AQtion AQC-107

Data Rates Supported 10/100/1000 Mbps, 2.5/5/10 Gbps PXE. UEFI

Boot ROM Support Connect Speed LED

Link/Activity LED

Indicators Off = No link

Blinking = Activity

Speed LED

Amber = < 10 Gbps

Green = 10Gbps

Management Capabilities Wake-On-LAN

Intel® I210-T1

Networking Interface RJ-45

System Interface PCI Express 2.1 x1

Networking Speeds

Cabling (up to 100m)

Supported

10Mbps, 100Mbps, 1Gbps

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption

0.81W

(active-typical)

Physical Dimensions Length: 6.7cm (2.64 inches)

(Bracket) Width: 1.8cm (0.709 inches)

Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)

Technical Specifications - Networking and Communications

Connect Speed LED Indicators

Link/Activity LED

- Off = No link
- Blinking = Activity

Speed LED

- Off = 10Mbps
- Green = 100Mbps
- Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications USA: FCC B, EU: UL CE.

Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® X550-T2

Networking Interface

2 x RJ-45

System Interface

PCI Express 3 x4

Networking Speeds

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cabling (up to 100m)

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

Power Consumption

(active-typical)

3.9W at 100Mbps 5.5W at 1Gbps

11.2W at 10Gbps

Physical Dimensions

Connect Speed LED

Indicators

Link/Activity LED

Off = No link

Blinking = Activity

5.2 in x 2.7 in (without bracket)

Speed LED

Off = No link

Amber = <10Gbps

Green = 10Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B. EU: UL CE, Japan: VCCI.

Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Technical Specifications - Networking and Communications

Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC

Networking Interface 1Gb LC Fiber 850 nm

System Interface PCIeG2 x1, Half Height, Half Length

Networking Speeds Supported 1000Base-X (1Gbps)

Cabling 50/125 μm (core/cladding) multimode fiber optic cable

up to 500m

62.5/125 μm (core/cladding) multimode fiber optic cable

up to 220m

Power Consumption (active-typical) 1.5 Watts

Physical Dimensions8.8 cm x 6.9 cm (3.5 in x 2.7 in)Connect Speed LED IndicatorsON: 1Gbps Link OFF: Link downOperating Temperature-25°C to 70°C (-13°F to 158°F)

Hardware Certifications IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs),

IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X),

IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-

TICK, VCCI

Date of change:	Version History:		Description of change:
December 17, 2020	From v1 to v2	Changed	Storage / Hard Drives and Graphics sections
February 1, 2021	From v2 to v3	Changed	Processors and NETWORKING AND COMMUNICATIONS sections
March 1, 2021	From v3 to v4	Changed	Overview and Other Hardware sections

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